

REMARKS

102 Rejections

Paragraph 2 of the above referenced office action states that Claim 1 is rejected under 35 U.S.C. § 102 as being clearly anticipated by Cote et al., U.S. Patent No. 5,534,106 (hereafter Cote). Applicants respectfully submit that the present invention as recited in Claims 1, 10, and new Claim 20 is not anticipated within the meaning of 35 U.S.C. § 102 by Cote.

Specifically, with respect to new Claim 20, Applicants respectfully submit that Cote does not show “a process specific polishing pad having a plurality of regions configured to achieve specific polishing processes effects when used in a wafer polishing machine” as specifically recited. Applicants respectfully assert that Cote does not show an overlying layer “...being uniform and homogenous across a polishing surface of said overlying layer...” as Claimed. Cote does not show a polishing surface of a polishing pad “...having a plurality of regions, each of said plurality of regions configured to achieve a specific process effect such that specific polishing effect can be achieved on said wafer by selectively moving said wafer frictionally one of said plurality of regions...” and further, does not show “each of said plurality of regions having a respective underlying layer adapted to achieve said specific process effect”. Applicant do not understand Cote to show underlying layers having different hardness beneath a uniform homogenous overlying layer. As explicitly claimed, the polishing surface of the present invention has an overlying layer providing a uniform homogenous quality across the area of its polishing surface. As such, Applicants respectfully assert that the present invention as recited in Claim 20 is not anticipated within the meaning of 35 U.S.C. § 102 by Cote.

103 Rejections

Paragraph 3 of the above referenced Office Action states that Claims 1, 3, 8, 10, 12, and 16 are rejected under 35 U.S.C. § 103(a) as being unpatentable over Cote et al. Cote does not disclose a linear pad as recited in dependent Claims 4, 9, and 17. In addition to not showing a linear pad, Applicants respectfully submit that Cote does not show a polishing pad having a combined first and second layers, the underlying layer having differing hardness beneath a uniform homogenous overlying layer as a single polishing pad. (Emphasis added) As such, Applicants respectfully assert that the present invention as recited in dependent Claims 9 and 17 is not shown, suggested, or rendered obvious by Cote within the meaning of 35 U.S.C. § 103(a).

Further, Applicants respectfully assert that claimed limitations describing the first and second underlying layers “having differing amounts of thickness when said wafer is frictionally moved against said polishing pad” to achieve the specific polishing effect are not shown by Cote. Applicants respectfully submit that underlying layers having different thickness as claimed is not shown or suggested by Cote.

Conclusion

In light of the above-listed new Claim 20 and remarks, Applicants respectfully request reconsideration of the rejected Claims. Applicants respectfully submit that all claims overcome the 35 U.S.C. § 102 rejections based on Cote and the 35 U.S.C. § 103 rejections based on Cote. Accordingly, Applicants submit that all claims are now in condition for allowance.

The Examiner is urged to contact Applicants' undersigned representative if the Examiner believes such action would expedite resolution of the present Application.

Please charge any additional fees or apply any credits to our PTO deposit account number: 23-0085.

Respectfully submitted,

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